

Model Name: EBA25001-10

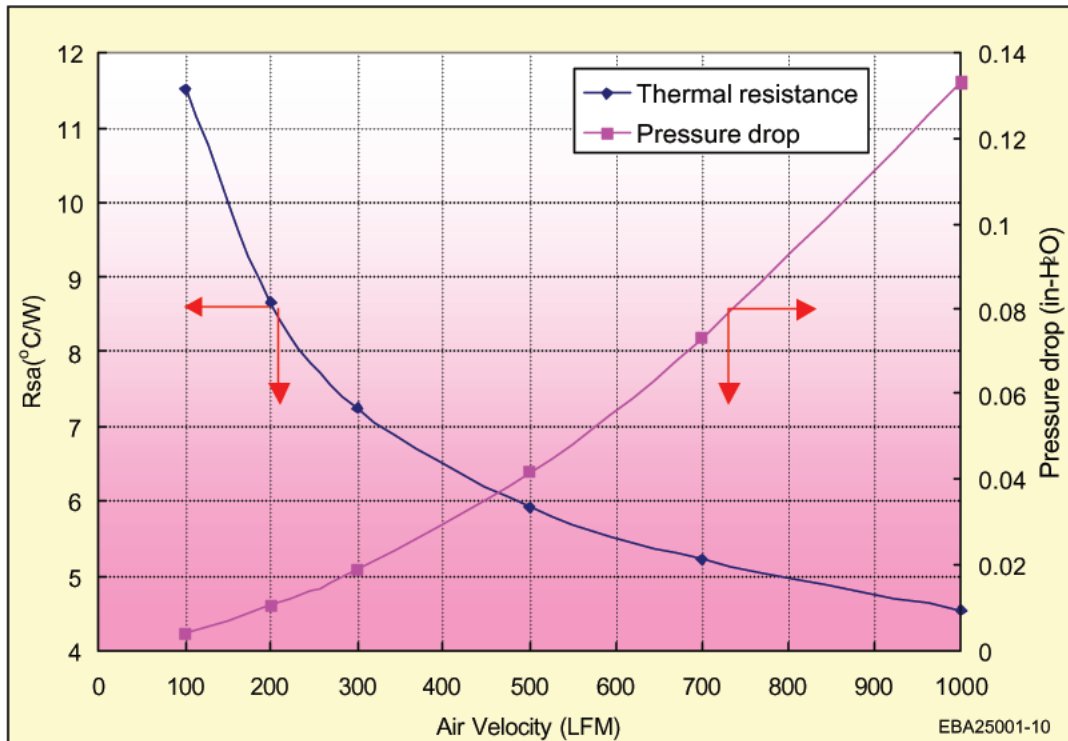
BGA Heat Sink For 25x25 Chip set

*Specification:

1. Material: Aluminum 6063
2. Weight: 6 gm
3. Technology: Extrusion
4. Finish: Black Anodize
5. Heat Sink Dimension:
24.7*24.6*9.8mm
6. Copper package and Moulding
compound package available
7. Heat Source size: Uniform



*Performance Data:



AMERICAN THERMAL PRODUCTS

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